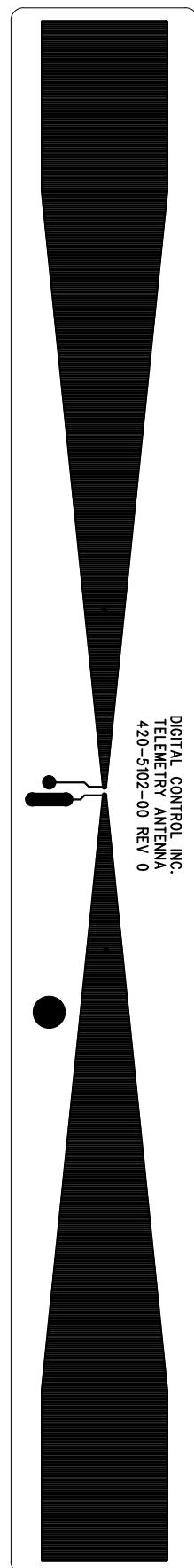


Statement from Digital Control Incorporated:

The DigiRadio™ module, designed for use in DigiTrak® brand handheld receivers (UHF transmitter) and remote displays (UHF receiver), is installed in the host devices at the manufacturer. The maximum gain antenna that is used with the DigiRadio module is also installed in the UHF transmitter host device at the manufacturer and is not accessible by the user. The antenna drawing is shown below.

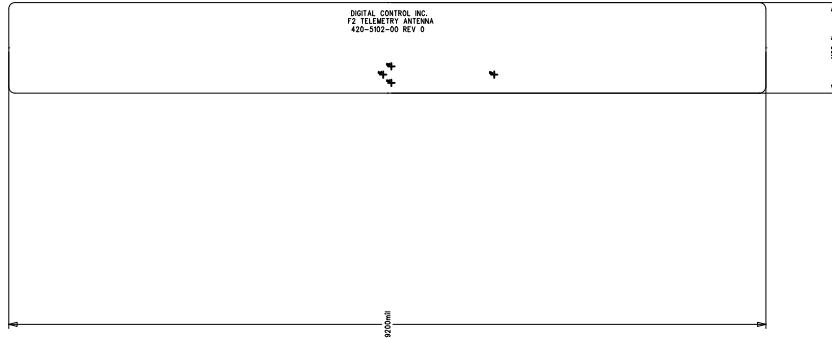


## PCB FABRICATION NOTES (UNLESS OTHERWISE SPECIFIED)

1. PRIMARY SIDE SHOWN.
2. TWO LAYER ROHS COMPLIANT PCB.
3. FABRICATE PER IPC-RB-276 IPC-6012, CLASS 2, CURRENT REV.
4. DETERMINE ACCEPTABILITY PER IPC-A-600, CLASS 2, CURRENT REV.
5. 25% BREAKOUT PERMITTED ON VIAS IF INTERFACE BETWEEN CONDUCTOR AND TERMINAL AREA OF PAD IS 100X.
6. MANUFACTURE/FABRICATE TO MEET THE RoHS DIRECTIVE. GLASS TRANSITION TEMPERATURE ( $T_g$ ) >70degC. DECOMPOSITION TEMPERATURE ( $T_d$ ) >345degC. MOISTURE ABSORPTION RATE  $< 0.35\%$  BOARD TO BE MEASURED OUTER METAL-TO-METAL THICKNESS.
7. TOOLING HOLES OF DIAMETER UP TO 0.126" PERMISSIBLE AND ARE NON-PLATED. IF PRESENT IN DESIGN, THEY SHALL BE MARKED "T". ALL OTHER HOLES SHALL BE PLATED OR NON-PLATED ACCORDING TO HOLE CHART.
8. HOLE SIZES GIVEN ARE FINISHED DIMENSIONS GIVEN IN THOUSANDS OF AN INCH. EXAMPLE: .35 SHALL BE READ AS .035".
9. SOLDERMASK BOTH SIDES OVER BARE COPPER PER IPC-SM-840, CLASS 2, CURRENT REV. AND MANUFACTURERS SPECIFICATIONS. TYPE: LIQUID PHOTOMAGEABLE . COLOR: GREEN.
10. NO SOLDER MASK PERMISSIBLE ON COMPONENT PADS AS PER SUPPLIED FILMWORK. FINISH: ELECTROLESS NICKEL/IMMERSION GOLD (ENIG).
11. 30 MICRONCHES MINIMUM OF HARD GOLD (99.7%) OVER 200 MICRONCHES OF NICKEL DATE CODE AND UL RECOGNIZED VENDOR MARK REQUIRED. DATE CODE SHALL USE FOUR NUMERALS, GIVING WORK WEEK AND YEAR, EG. 2898 STANDS FOR THE 28TH WEEK OF 1998. THESE MARKS SHALL BE MADE IN COPPER AND SHALL BE LOCATED ON THE SECONDARY SIDE OF THE PCB.
12. SCREEN COMPONENT ID WITH NON-CONDUCTING WHITE INK. COMPONENT ID REGISTRATION TO BE WITHIN  $+/- 0.005"$  OF ITS RESPECTIVE COMPONENT LAYER. NO SILKSCREEN INK PERMISSIBLE ON COMPONENT PADS OR IN PADS AS PER SUPPLIED FILMWORK.
13. ETCH TOLERANCE  $+0.001" - 0.002"$ . TOTAL TRACE REDUCTION CANNOT EXCEED 20%.
14. FRONT-TO-BACK REGISTRATION TO BE WITHIN  $+/- 0.003"$ .
15. BOARD WARP TO BE NO GREATER THAN  $12\%$ .
16. HOLE TOLERANCES

UP TO 0.018" DIA	$+0.000/-0.003"$
0.020 - 0.049" DIA	$+/-0.003"$
0.050 - 0.099" DIA	$+/-0.005"$
0.100" AND UP	$+/-0.007"$

17. LAYER CONFIGURATION DIAGRAM:  
PRIMARY SIDE COMPONENT ID:  
PRIMARY SIDE SOLDER MASK  
CIRCUIT LAYER #1 (PRIMARY SIDE)  
CIRCUIT LAYER #2 (SECONDARY SIDE)  
SECONDARY SIDE SOLDER MASK  
SECONDARY SIDE SILK SCREEN



CONFIDENTIAL

DRAWING #	08-11-08	TITLE:	
CHECKED:		DRAWING NO.:	420-5102-00
QC:		SCALE:	0
RELEASED:		HE:	SHEET 1 OF 1

SIZE	QTY	SYN	PLATED	TOL
49	3	<input checked="" type="checkbox"/>	YES	$+/-0.0$
125	1	<input checked="" type="checkbox"/>	YES	$+/-0.0$

